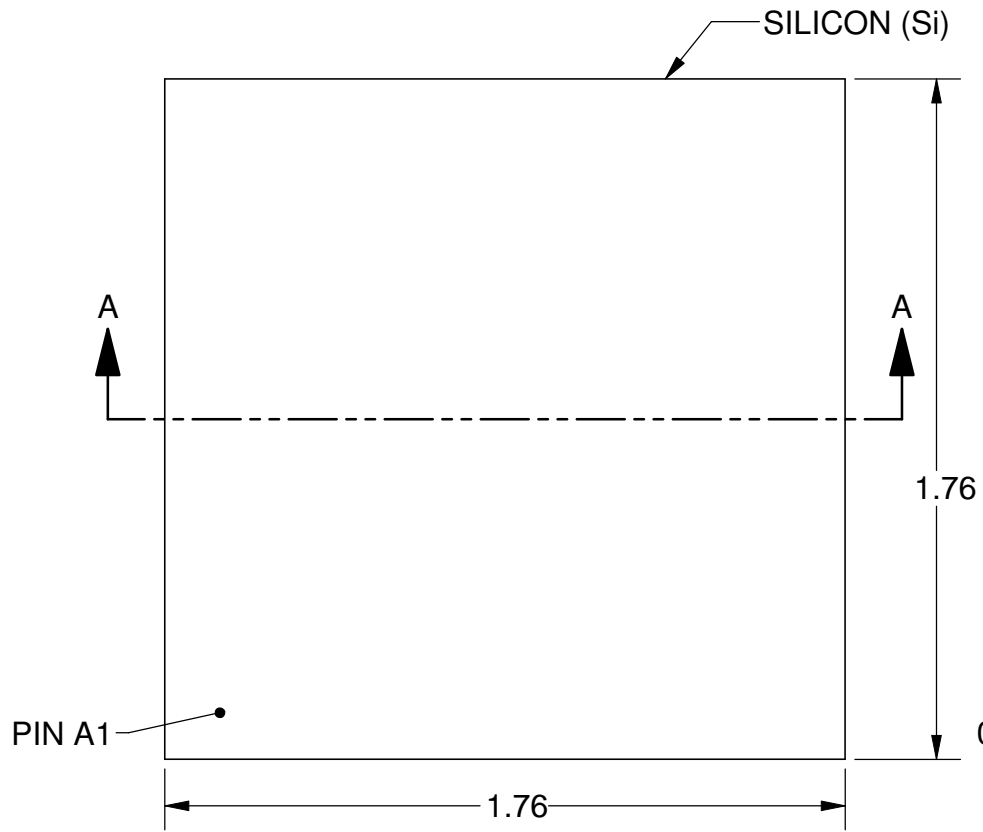
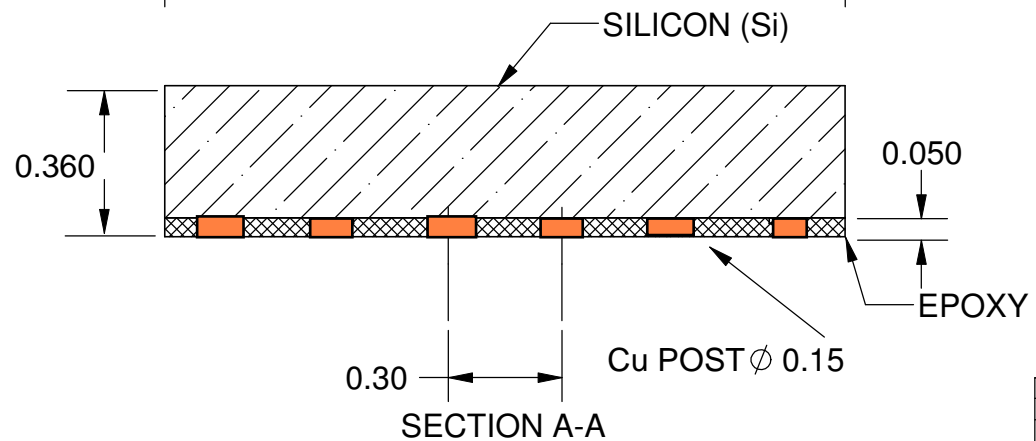
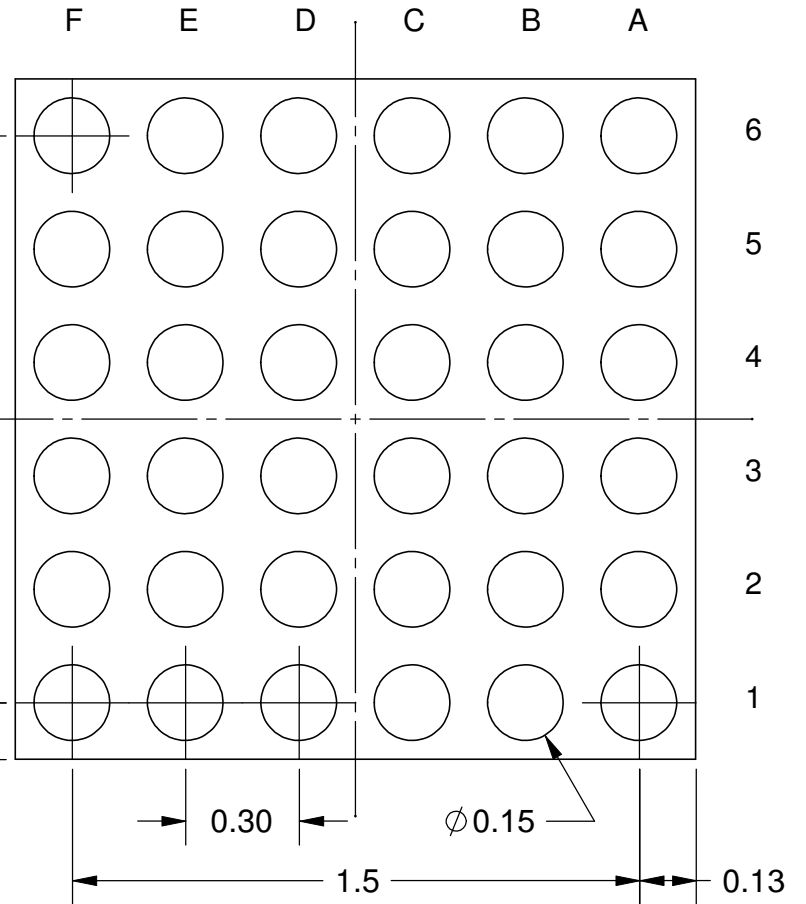


TOP VIEW



PAD VIEW



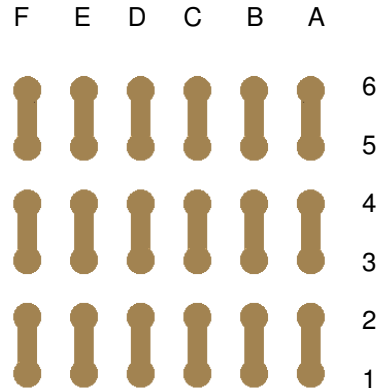
Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) PAD ALLOY: Cu (50um Thick)

3) PAD Cu DIAMETER: 0.15mm.
 4) DIE MATERIAL: Si (SILICON).
 5) DAISY CHAIN PATTERN (SEE PAGE 2).

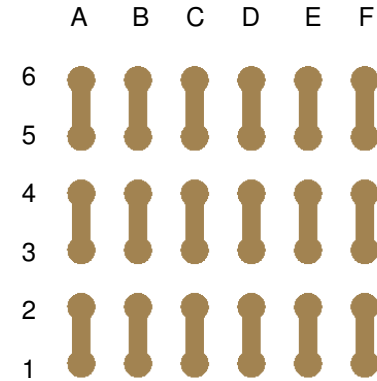
TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.3	DRAWN J. Hines		12/29/2010						TITLE
X.XX	+/- 0.03	ENG				eWLP36T.3-DC067D3				
X.XXX	+/- 0.003	MFG				36-L P=0.3mm (TEG0306)				
ANGLES +/- 0.5°		QA		SCALE		SIZE		DRAWING NO.		REV
ALL DIMENSIONS IN		CUST		50:1		A		730670		A
☐ INCHES ☒ MILLIMETERS		REVISED								
THIRD ANGLE PROJECTION										
						DO NOT SCALE DRAWING		SHEET 1 OF 2		

DAISY CHAIN PATTERN

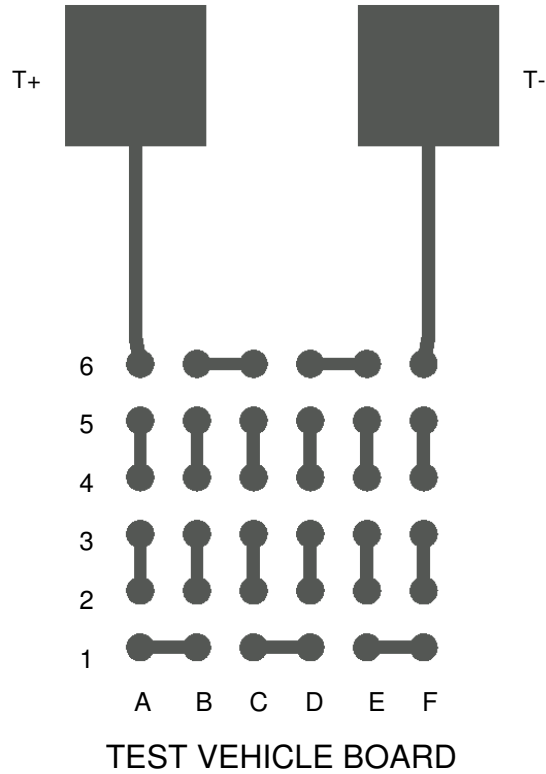
PAD VIEW



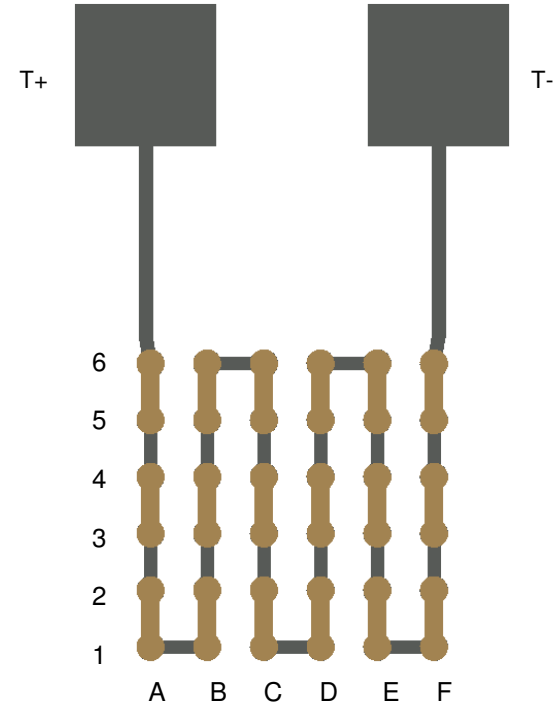
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine [®]			
TITLE eWLP36T.3-DC067D3 36L- P=0.3mm (TEG0306)			
SCALE 25:1	SIZE A	DRAWING NO. 730670	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 2